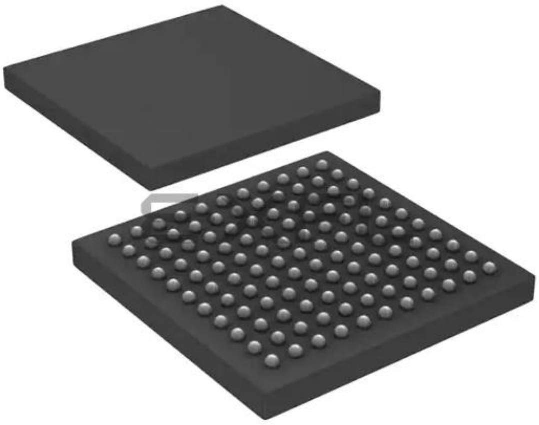
Microchip Technology - PIC32MX460F512LT-80V/BG Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	-
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	121-TFBGA
Supplier Device Package	121-TFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx460f512lt-80v-bg

TABLE 4: PIN NAMES: PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES

Pin Number	Full Pin Name
A1	PMD4/RE4
A2	PMD3/RE3
A3	TRD0/RG13
A4	PMD0/RE0
A5	PMD8/RG0
A6	PMD10/RF1
A7	ENVREG
A8	VSS
A9	IC5/PMD12/RD12
A10	OC3/RD2
A11	OC2/RD1
B1	No Connect (NC)
B2	RG15
B3	PMD2/RE2
B4	PMD1/RE1
B5	TRD3/RA7
B6	PMD11/RF0
B7	VCAP/VCORE
B8	PMRD/CN14/RD5
B9	OC4/RD3
B10	VSS
B11	SOSCO/T1CK/CN0/RC14
C1	PMD6/RE6
C2	VDD
C3	TRD1/RG12
C4	TRD2/RG14
C5	TRCLK/RA6
C6	No Connect (NC)
C7	PMD15/CN16/RD7
C8	OC5/PMWR/CN13/RD4
C9	VDD
C10	SOSCI/CN1/RC13
C11	IC4/PMCS1/PMA14/RD11
D1	T2CK/RC1
D2	PMD7/RE7
D3	PMD5/RE5
D4	VSS
D5	VSS
D6	No Connect (NC)
D7	PMD14/CN15/RD6
D8	CN19/PMD13/RD13
D9	SDO1/OC1/INT0/RD0
D10	No Connect (NC)
D11	SCK1/IC3/PMCS2/PMA15/RD10
E1	T5CK/SDI1/RC4
E2	T4CK/RC3
E3	SCK2/PMA5/CN8/RG6
E4	T3CK/RC2
E5	VDD
E6	PMD9/RG1
E7	VSS
E8	SDA1/INT4/RA15
E9	RTCC/IC1/RD8
E10	$\overline{\text{SS1}}$/IC2/RD9
E11	SCL1/INT3/RA14
F1	$\overline{\text{MCLR}}$
F2	SDO2/PMA3/CN10/RG8
F3	$\overline{\text{SS2}}$/PMA2/CN11/RG9
F4	SDI2/PMA4/CN9/RG7
F5	VSS
F6	No Connect (NC)
F7	No Connect (NC)
F8	Vdd
F9	OSC1/CLKI/RC12
F10	VSS
F11	OSC2/CLKO/RC15
G1	INT1/RE8
G2	INT2/RE9
G3	TMS/RA0
G4	No Connect (NC)
G5	VDD
G6	VSS
G7	VSS
G8	No Connect (NC)
G9	TDO/RA5
G10	SDA2/RA3
G11	TDI/RA4
H1	AN5/C1IN+/VBUSON/CN7/RB5
H2	AN4/C1IN-/CN6/RB4
H3	VSS
H4	VDD
H5	No Connect (NC)
H6	VDD
H7	No Connect (NC)
H8	VBUS
H9	VUSB
H10	D+/RG2
H11	SCL2/RA2
J1	AN3/C2IN+/CN5/RB3
J2	AN2/C2IN-/CN4/RB2
J3	PGED2/AN7/RB7
J4	AVDD
J5	AN11/PMA12/RB11
J6	TCK/RA1
J7	AN12/PMA11/RB12
J8	No Connect (NC)
J9	No Connect (NC)
J10	U1TX/RF8
J11	D-/RG3
K1	PGEC1/AN1/CN3/RB1
K2	PGED1/AN0/CN2/RB0
K3	VREF+/CVREF+/PMA6/RA10

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number[1]			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
INT3	44	66	E11	I	ST	External interrupt 3.
INT4	45	67	E8	I	ST	External interrupt 4.
RA0	—	17	G3	I/O	ST	PORTA is a bidirectional I/O port.
RA1	—	38	J6	I/O	ST	
RA2	—	58	H11	I/O	ST	
RA3	—	59	G10	I/O	ST	
RA4	—	60	G11	I/O	ST	
RA5	—	61	G9	I/O	ST	
RA6	—	91	C5	I/O	ST	
RA7	—	92	B5	I/O	ST	
RA9	—	28	L2	I/O	ST	
RA10	—	29	K3	I/O	ST	
RA14	—	66	E11	I/O	ST	
RA15	—	67	E8	I/O	ST	
RB0	16	25	K2	I/O	ST	PORTB is a bidirectional I/O port.
RB1	15	24	K1	I/O	ST	
RB2	14	23	J2	I/O	ST	
RB3	13	22	J1	I/O	ST	
RB4	12	21	H2	I/O	ST	
RB5	11	20	H1	I/O	ST	
RB6	17	26	L1	I/O	ST	
RB7	18	27	J3	I/O	ST	
RB8	21	32	K4	I/O	ST	
RB9	22	33	L4	I/O	ST	
RB10	23	34	L5	I/O	ST	
RB11	24	35	J5	I/O	ST	
RB12	27	41	J7	I/O	ST	
RB13	28	42	L7	I/O	ST	
RB14	29	43	K7	I/O	ST	
RB15	30	44	L8	I/O	ST	
RC1	—	6	D1	I/O	ST	PORTC is a bidirectional I/O port.
RC2	—	7	E4	I/O	ST	
RC3	—	8	E2	I/O	ST	
RC4	—	9	E1	I/O	ST	
RC12	39	63	F9	I/O	ST	
RC13	47	73	C10	I/O	ST	
RC14	48	74	B11	I/O	ST	
RC15	40	64	F11	I/O	ST	

Legend:
CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer
Analog = Analog input
O = Output
P = Power
I = Input

Note 1: Pin numbers are provided for reference only. See the **“Pin Diagrams”** section for device pin availability.

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MICROCONTROLLERS

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the PIC32MX3XX/4XX family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used) (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP/VCORE (see **Section 2.3 "Capacitor on Internal Voltage Regulator (VCAP/VCORE)"**)
- $\overline{\text{MCLR}}$ pin (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used (see **Section 2.8 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins used when external voltage reference for ADC module is implemented

Note: The AVDD and AVSS pins must be connected independent of ADC use and ADC voltage reference source.

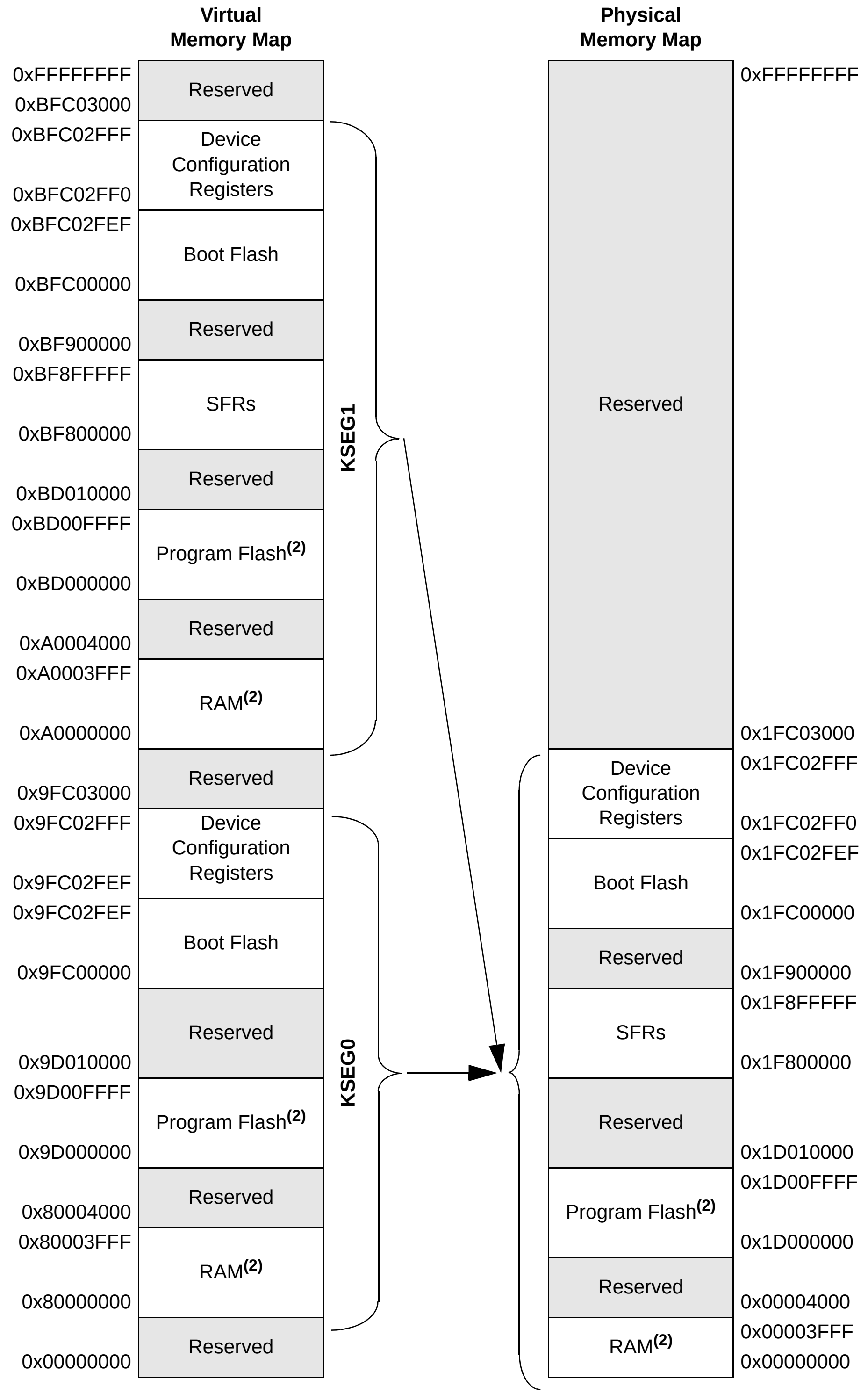
2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

FIGURE 4-2: MEMORY MAP ON RESET FOR PIC32MX320F064H DEVICE(1)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS61115)) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

TABLE 4-4: INTERRUPT REGISTERS MAP FOR PIC32MX320F032H, PIC32MX320F064H, PIC32MX320F128H AND PIC32MX320F128L DEVICES ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	SPI1RXIF	SPI1TXIF	SPI1EIF	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	—	FCEIF	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	SPI1RXIE	SPI1TXIE	SPI1EIE	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	—	FCEIE	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	—	—	—	—	—	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>		—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>		—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	SPI1IP<2:0>			SPI1IS<1:0>		—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>		—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>		—	—	—	CNIP<2:0>			CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>		—	—	—	U1IP<2:0>			U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>		—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>		—	—	—	PMPIP<2:0>			PMPIS<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>		—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>		—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-16: DMA CHANNELS 0-3 REGISTERS MAP FOR PIC32MX340FXXXX/360FXXXX/440FXXXX/460XXXX DEVICES ONLY[(1)] (CONTINUED)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3160	DCH1DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
3170	DCH1SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSSIZ<7:0>								0000
3180	DCH1DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDSIZ<7:0>								0000
3190	DCH1SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSPTR<7:0>								0000
31A0	DCH1DPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDPTR<7:0>								0000
31B0	DCH1CSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHCSIZ<7:0>								0000
31C0	DCH1CPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHCPTR<7:0>								0000
31D0	DCH1DAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHPDAT<7:0>								0000
31E0	DCH2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	CHCHNS	CHEN	CHAED	CHCHN	CHAEN	—	CHEDET	CHPRI<1:0>		0000
31F0	DCH2ECON	31:16	—	—	—	—	—	—	—	—	CHAIRQ<7:0>								00FF
		15:0	CHSIRQ<7:0>								CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—	FF00
3200	DCH2INT	31:16	—	—	—	—	—	—	—	—	CHSDIE	CHSHIE	CHDDIE	CHDHIE	CHBCIE	CHCCIE	CHTAIE	CHERIE	0000
		15:0	—	—	—	—	—	—	—	—	CHSDIF	CHSHIF	CHDDIF	CHDHIF	CHBCIF	CHCCIF	CHTAIF	CHERIF	0000
3210	DCH2SSA	31:16	CHSSA<31:0>																0000
		15:0																	0000
3220	DCH2DSA	31:16	CHDSA<31:0>																0000
		15:0																	0000
3230	DCH2SSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSSIZ<7:0>								0000
3240	DCH2DSIZ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHDSIZ<7:0>								0000
3250	DCH2SPTR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	CHSPTR<7:0>								0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers except DCHxSPTR, DCHxDPTR and DCHxCPTR have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-31: PORTF REGISTERS MAP FOR PIC32MX320F032H, PIC32MX320F064H, PIC32MX320F128H, PIC32MX340F128H, PIC32MX340F256H AND PIC32MX340F512H DEVICES ONLY[1]

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6140	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	07FF
6150	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	RF6	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6160	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	LATF6	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6170	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	ODCF6	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-32: PORTF REGISTERS MAP FOR PIC32MX420F032H, PIC32MX440F128H AND PIC2MX440F256H DEVICES ONLY[1]

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6140	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	03FF
6150	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6160	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6170	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

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REGISTER 26-3: DEVCFG2: DEVICE CONFIGURATION WORD 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
23:16	r-1	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	—	—	—	—	—	FPLLODIV<2:0>		
15:8	R/P	r-1	r-1	r-1	r-1	R/P	R/P	R/P
	UPLLEN	—	—	—	—	UPLLIDIV<2:0>		
7:0	r-1	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	—	FPLLMUL<2:0>			—	FPLLIDIV<2:0>		

Legend:
R = Readable bit W = Writable bit P = Programmable bit r = Reserved bit
U = Unimplemented bit -n = Bit Value at POR: (‘0’, ‘1’, x = Unknown)

bit 31-19 **Reserved:** Write ‘1’

bit 18-16 **FPLLODIV<2:0>:** Default Postscaler for PLL bits
`111` = PLL output divided by 256
`110` = PLL output divided by 64
`101` = PLL output divided by 32
`100` = PLL output divided by 16
`011` = PLL output divided by 8
`010` = PLL output divided by 4
`001` = PLL output divided by 2
`000` = PLL output divided by 1

bit 15 **UPLLEN:** USB PLL Enable bit
`1` = Disable and bypass USB PLL
`0` = Enable USB PLL

bit 14-11 **Reserved:** Write ‘1’

bit 10-8 **UPLLIDIV<2:0>:** PLL Input Divider bits
`111` = 12x divider
`110` = 10x divider
`101` = 6x divider
`100` = 5x divider
`011` = 4x divider
`010` = 3x divider
`010` = 3x divider
`001` = 2x divider
`000` = 1x divider

bit 7 **Reserved:** Write ‘1’

bit 6-4 **FPLLMUL<2:0>:** PLL Multiplier bits
`111` = 24x multiplier
`110` = 21x multiplier
`101` = 20x multiplier
`100` = 19x multiplier
`011` = 18x multiplier
`010` = 17x multiplier
`001` = 16x multiplier
`000` = 15x multiplier

bit 3 **Reserved:** Write ‘1’

bit 2-0 **FPLLIDIV<2:0>:** PLL Input Divider bits
`111` = 12x divider
`110` = 10x divider
`101` = 6x divider
`100` = 5x divider
`011` = 4x divider
`010` = 3x divider
`001` = 2x divider
`000` = 1x divider

NOTES:

28.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB C Compiler for Various Device Families
  - HI-TECH C for Various Device Families
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
  - MPLAB ICD 3
  - PICkit™ 3 Debug Express
- Device Programmers
  - PICkit™ 2 Programmer
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

28.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - In-Circuit Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
  - Source files (C or assembly)
  - Mixed C and assembly
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

29.1 DC Characteristics

TABLE 29-1: OPERATING MIPS VS. VOLTAGE

Characteristic	V_{DD} Range (in Volts)	Temp. Range (in °C)	Max. Frequency
			PIC32MX3XX/4XX
DC5	2.3V-3.6V	-40°C to +85°C	80 MHz **(Note 1)**
DC5b	2.3V-3.6V	-40°C to +105°C	80 MHz **(Note 1)**

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

TABLE 29-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	T_J	-40	—	+125	°C
Operating Ambient Temperature Range	T_A	-40	—	+85	°C
V-Temp Temperature Devices					
Operating Junction Temperature Range	T_J	-40	—	+140	°C
Operating Ambient Temperature Range	T_A	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - S\ I_{OH})$ I/O Pin Power Dissipation: $I/O = S\ (\{V_{DD} - V_{OH}\} \times I_{OH}) + S\ (V_{OL} \times I_{OL})$	P_D	$P_{INT} + P_{I/O}$			W
Maximum Allowed Power Dissipation	P_{DMAX}	$(T_J - T_A)/\theta_{JA}$			W

TABLE 29-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 121-Pin XBGA (10x10x1.1 mm)	θ_{JA}	40	—	°C/W	**1**
Package Thermal Resistance, 100-Pin TQFP (12x12x1 mm)	θ_{JA}	43	—	°C/W	**1**
Package Thermal Resistance, 64-Pin TQFP (10x10x1 mm)	θ_{JA}	47	—	°C/W	**1**
Package Thermal Resistance, 64-Pin QFN (9x9x0.9 mm)	θ_{JA}	28	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-JA (θ_{JA}) numbers are achieved by package simulations.

TABLE 29-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
Operating Voltage							
DC10	V_{DD}	**Supply Voltage**	2.3	—	3.6	V	—
DC12	V_{DR}	**RAM Data Retention Voltage (Note 1)**	1.75	—	—	V	—
DC16	V_{POR}	**V_{DD} Start Voltage** to Ensure Internal Power-on Reset Signal	1.75	—	1.95	V	—
DC17	S_{VDD}	**V_{DD} Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	—

Note 1: This is the limit to which V_{DD} can be lowered without losing RAM data.

TABLE 29-17: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical[1]**	**Max.**	**Units**	**Conditions**
OS10	FOSC	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50[3] 50[5]	MHz MHz	EC **(Note 5)** ECPLL **(Note 4)**
OS11		Oscillator Crystal Frequency	3	—	10	MHz	XT **(Note 5)**
OS12			4	—	10	MHz	XTPLL **(Notes 4, 5)**
OS13			10	—	25	MHz	HS **(Note 5)**
OS14			10	—	25	MHz	HSPLL **(Notes 4, 5)**
OS15			32	32.768	100	kHz	SOSC **(Note 5)**
OS20	TOSC	TOSC = 1/FOSC = TCY[2]	—	—	—	—	See parameter OS10 for FOSC value
OS30	TOSL, TOSH	External Clock In (OSC1) High or Low Time	0.45 x TOSC	—	—	ns	EC **(Note 5)**
OS31	TOSR, TOSF	External Clock In (OSC1) Rise or Fall Time	—	—	0.05 x TOSC	ns	EC **(Note 5)**
OS40	TOST	Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and SOSC Clock Oscillator modes)	—	1024	—	TOSC	**(Note 5)**
OS41	TFSCM	Primary Clock Fail Safe Time-out Period	—	2	—	ms	**(Note 5)**
OS42	GM	External Oscillator Transconductance	—	12	—	mA/V	VDD = 3.3V TA = +25°C **(Note 5)**

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

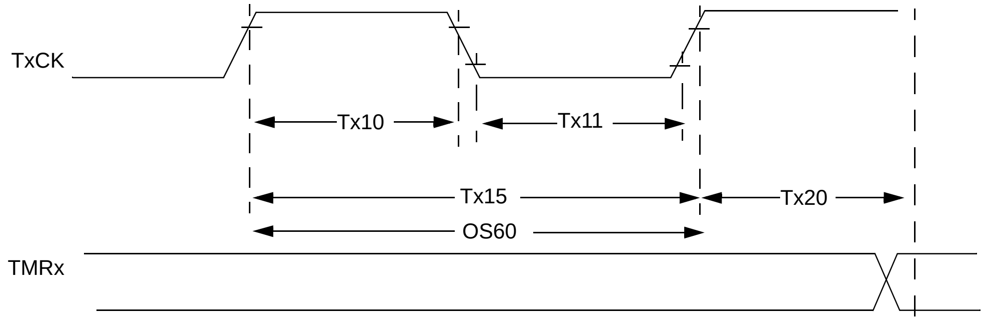
2: Instruction cycle period (TCY) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKI pin.

3: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

4: PLL input requirements: 4 MHZ ≤ FPLLIN ≤ 5 MHZ (use PLL prescaler to reduce FOSC). This parameter is characterized, but tested at 10 MHz only at manufacturing.

5: This parameter is characterized, but not tested in manufacturing.

FIGURE 29-6: TIMER1, 2, 3, 4, 5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 29-1 for load conditions.

TABLE 29-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS[1]

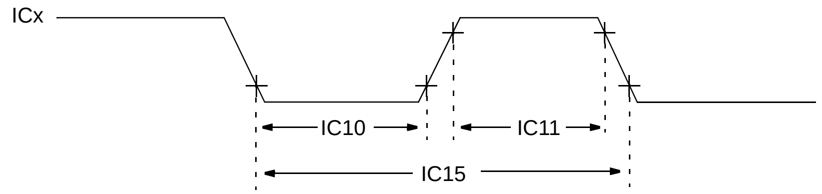
AC CHARACTERISTICS				**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics[2]**		**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
TA10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	—	ns	Must also meet parameter TA15.
			Asynchronous, with prescaler	10	—	—	ns	—
TA11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	—	ns	Must also meet parameter TA15.
			Asynchronous, with prescaler	10	—	—	ns	—
TA15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of 25 ns or 2TPB)/N] + 30 ns	—	—	ns	VDD > 2.7V
				[(Greater of 25 ns or 2TPB)/N] + 50 ns	—	—	ns	VDD < 2.7V
			Asynchronous, with prescaler	20	—	—	ns	VDD > 2.7V **(Note 3)**
				50	—	—	ns	VDD < 2.7V **(Note 3)**
OS60	FT1	SOSC1/T1CK Oscillator Input Frequency Range (oscillator enabled by setting TCS bit (T1CON<1>))		32	—	100	kHz	—
TA20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—		1	TPB	—

Note 1: Timer1 is a Type A.

2: This parameter is characterized, but not tested in manufacturing.

3: N = prescale value (1, 8, 64, 256)

FIGURE 29-7: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS



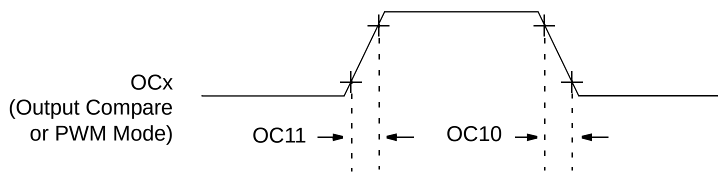
Note: Refer to Figure 29-1 for load conditions.

TABLE 29-25: INPUT CAPTURE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**[1]	**Min.**	**Max.**	**Units**	**Conditions**	
IC10	TCCL	ICx Input Low Time	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	N = prescale value (1, 4, 16)
IC11	TCCH	ICx Input High Time	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter IC15.	
IC15	TCCP	ICx Input Period	[(25 ns or 2TPB)/N] + 50 ns	—	ns	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 29-8: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 29-1 for load conditions.

TABLE 29-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**[1]	**Min.**	**Typical**[2]	**Max.**	**Units**	**Conditions**
OC10	TCCF	OCx Output Fall Time	—	—	—	ns	See parameter DO32.
OC11	TCCR	OCx Output Rise Time	—	—	—	ns	See parameter DO31.

Note 1: These parameters are characterized, but not tested in manufacturing.

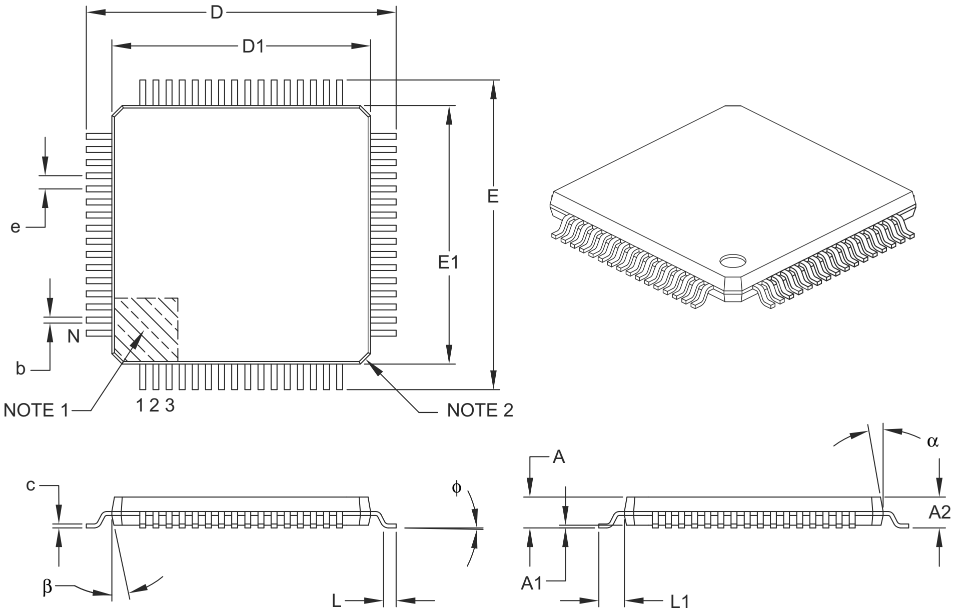
2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

30.2 Package Details

The following sections give the technical details of the packages.

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Leads	N	64		
Lead Pitch	e	0.50 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	φ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

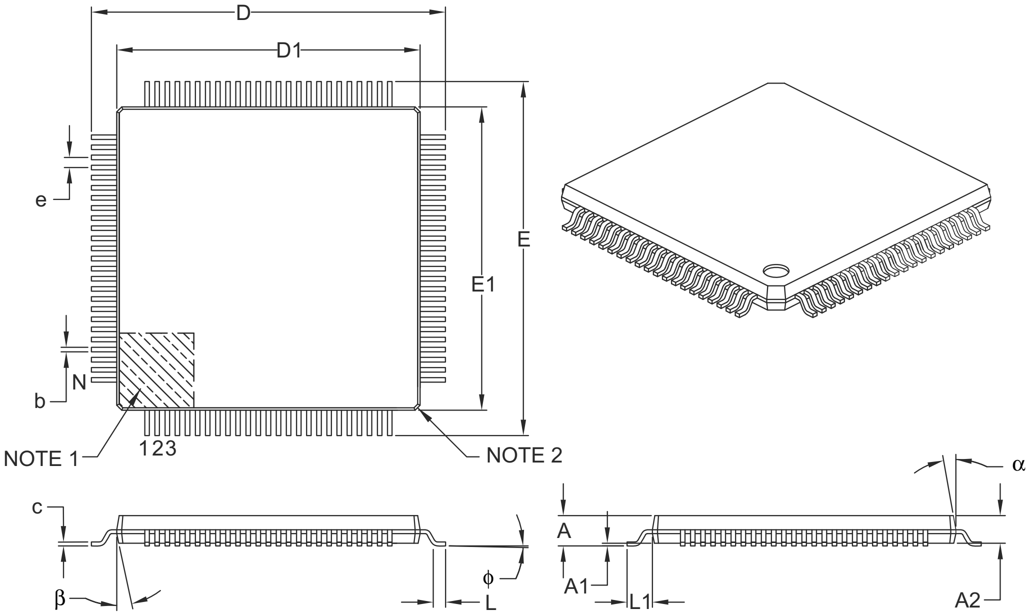
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	100		
Lead Pitch	e	0.40 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E	14.00 BSC		
Overall Length	D	14.00 BSC		
Molded Package Width	E1	12.00 BSC		
Molded Package Length	D1	12.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 29.0 “Electrical Characteristics”	Updated the Absolute Maximum Ratings and added Note 3. Added Thermal Packaging Characteristics for the 121-pin XBGA package (see Table 29-3). Updated the conditions for parameters DC20, DC21, DC22 and DC23 in Table 29-5. Updated the comments for parameter D321 (CEFC) in Table 29-15. Updated the SPIx Module Slave Mode (CKE = 1) Timing Characteristics, changing SP52 to SP35 between the MSb and Bit 14 on SDOx (see Figure 29-13).
Section 30.0 “Packaging Information”	Added the 121-pin XBGA package marking information and package details.
“Product Identification System”	Added the definition for BG (121-lead 10x10x1.1 mm, XBGA). Added the definition for Speed.